

FEATURES

- Compact, high resolution absolute encoder ICs for up to 23 bit singleturn resolution (with nonius interpolation)
- \blacklozenge For code discs of \varnothing 18 mm, \varnothing 26 mm, \varnothing 33 mm, \varnothing 39 mm
- Monolithic 3-channel HD Phased Array with excellent signal matching
- Moderate track pitch for reduced cross talk
- Ultra low dark currents for operation up to high temperature
- Low noise amplifiers with high transimpedance gain
- Enhanced EMI tolerance by low impedance differential, short-circuit-proof, analog sine/cosine outputs
- ♦ Low power consumption from single 4.1 to 5.5 V supply
- Operational temperature range of -40 °C to +125 °C
- Space saving optoQFN and optoBGA packages (RoHS compliant)
- Evaluation kits with LED and code disc available for sampling

APPLICATIONS

Absolute position encoders

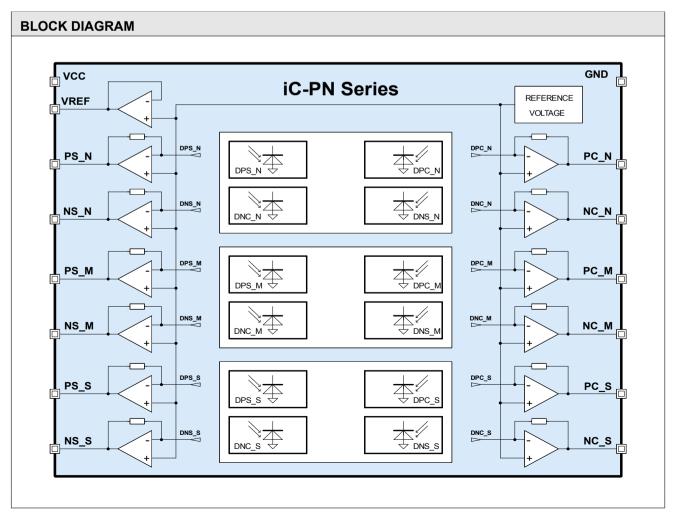
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AC servo feedback

PACKAGES



RoHS compliant





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DESCRIPTION

The iC-PN device series represents advanced optical encoder ICs featuring monolithically integrated photosensors arranged as an *HD Phased Array*, providing excellent signal fidelity at relaxed alignment tolerances.

Precise sine/cosine output signals allow for a high-resolution interpolation by subsequent devices: depending on the iC-PN version, a singleturn position can be resolved with up to 23 bit utilizing the 3-channel nonius interpolation of iC-MN.

The typical application of iC-PN devices are absolute position encoders for motion control and drive applications.

The iC-PN scans 3 incremental tracks by a phased-array of multiple photosensors each per track, and generates positive and negative going sine signals, as well as positive and negative going cosine signals. An excellent matching and common mode behavior of the differential signal paths is obtained by a paired amplifier design. Due to a typical transimpedance gain of $1 M\Omega$, the output signal level reaches a few hundred millivolts already at low light conditions.

iC-PN18xx Series - preliminary

Optical radius 6.9 mm, code disc Ø 18.0 mm; iC-PN1864: 64 CPR (63/64/56 CPR) iC-PN1856: 256 CPR (255/256/240 CPR)

iC-PN26xx Series

Optical radius 10.9 mm, code disc Ø 26.0 mm; iC-PN2656: 256 CPR (256/255/240 CPR) iC-PN2612: 512 CPR (511/512/496 CPR) iC-PN2624: 1024 CPR (1023/1024/992 CPR)

iC-PN33xx Series

Optical radius 14.5 mm, code disc Ø 33.0 mm; iC-PN3356: 256 CPR (256/255/240 CPR) iC-PN3312: 512 CPR (511/512/496 CPR) iC-PN3324: 1024 CPR (1023/1024/992 CPR)

iC-PN39xx Series

Optical radius 17.5 mm, code disc Ø 39.0 mm; iC-PN3924: 1024 CPR (1023/1024/992 CPR)

PACKAGING INFORMATION

PAD LAYOUT

∩ vcc 0 PC_M() PC_S () ⊖ns_s NC_S

PAD FUNCTIONS No. Name Function

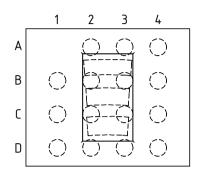
Chip layout example. Grey sections represent sensor layout areas; fill factors vary.





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PIN CONFIGURATION oBGA LSH2C (6.2 mm x 5.2 mm)

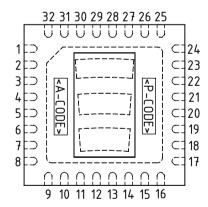


PIN FUNCTIONS

- No. Name Function
- A2 VCC +4.1..5.5 V Supply Voltage A3 VREF Reference Voltage Output A4 GND Ground
- B1 PS N N-Track Sine +
- B2 NS N N-Track Sine -
- B3 NC_N N-Track Cosine -
- B4 PC_N N-Track Cosine +
- C1 PS_M M-Track Sine +
- C2 NS_M M-Track Sine -
- C3 NC_M M-Track Cosine -
- C4 PC_M M-Track Cosine +
- D1 PS_S S-Track Sine +
- D2 NS_S S-Track Sine -
- D3 NC_S S-Track Cosine -
- D4 PC_S S-Track Cosine + Note: All signal outputs are analog voltage outputs.

For dimensional specifications refer to the relevant package data sheet, available separately.

PIN CONFIGURATION oQFN32-5x5 (5 mm x 5 mm)



PIN FUNCTIONS

No. Name Function

- 1 VCC +4.1..5.5 V Supply Voltage
- 2 VREF Reference Voltage Output
- 3 PS_N N-Track Sine +
- 4 NS_N N-Track Sine -
- 5 PS M M-Track Sine +
- 6 NS M M-Track Sine -
- 7 PS S S-Track Sine +
- 8 NS S S-Track Sine -
- 9..16 n.c.¹)
 - 17 NC_S S-Track Cosine -
 - 18 PC S S-Track Cosine +
 - 19 NC M M-Track Cosine -
 - 20 PC M M-Track Cosine +
 - 21 NC N N-Track Cosine -
 - 22 PC N N-Track Cosine +
- 23 n.c.¹)
- 24 GND Ground
- 25..32 n.c.¹⁾

BP²⁾ Backside paddle

IC top marking: <P-CODE> = product code, <A-CODE> = assembly code (subject to changes); 1) Pin numbers marked n.c. are not connected.

2) Connecting the backside paddle is recommended by a single link to GND. A current flow across the paddle is not permissible.

0.30

PACKAGE DIMENSIONS oQFN32-5x5

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3.60 4.90

RECOMMENDED PCB-FOOTPRINT 4.90 3.60 R0.15 ŧ⊨ SIDE ±0.10 0.60 0.70 0.50 0.30 TOP BOTTOM 5 1.90 3.60 Π IJ U U U 5 3.60 3.24 ഹ C D C ĥ ĥ \cap 0.4.0 0.50 0.23

All dimensions given in mm. Tolerances of form and position according to JEDEC MO-220. Positional tolerance of sensor pattern: $\pm 70\mu$ m / $\pm 1^{\circ}$ (with respect to backside pad). G4: radius of chip center (refer to the relevant encoder disc and code description). Maximum molding excess $\pm 20\mu$ m / -75μ m versus surface of glass/reticle.

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ABSOLUTE MAXIMUM RATINGS

These ratings do not imply operating conditions; functional operation is not guaranteed. Beyond these ratings device damage may occur.

Item	Symbol	Parameter	Conditions			Unit
No.				Min.	Max.	
G001	VCC	Voltage at VCC		-0.3	6	V
G002	I(VCC)	Current in VCC		-20	20	mA
G003	V()	Pin Voltage, all signal outputs		-0.3	VCC + 0.3	V
G004	I()	Pin Current, all signal outputs		-20	20	mA
G005	Vd()	ESD Susceptibility, all pins	HBM, 100 pF discharged through $1.5 \text{ k}\Omega$		2	kV
G006	Тј	Junction Temperature		-40	150	°C
G007	Ts	Chip Storage Temperature		-40	150	°C

THERMAL DATA

Operating conditions: VCC = 4.1...5.5 V

ltem	Symbol	Parameter	Conditions				Unit
No.				Min.	Тур.	Max.	
T01	Та	Operating Ambient Temperature Range		-40		125	°C
			package oBGA LSH2C	-40		110	°C
T02	Ts	Storage Temperature Range	package oQFN32-5x5 package oBGA LSH2C	-40 -40		125 110	°C °
T03	Tpk	Soldering Peak Temperature	package oQFN32-5x5				
			tpk < 20 s, convection reflow tpk < 20 s, vapor phase soldering			245 230	С С
1			MSL 5A (max. floor life 24 h at 30 °C and 60 % RH); Please refer to customer information file No. 7 for details.				
T04	Tpk	Soldering Peak Temperature	package oBGA LSH2C				
			tpk < 20 s, convection reflow tpk < 20 s, vapor phase soldering			245 230	ວ° ວ°
			TOL (time on label) 8 h; Please refer to customer information file No. 7 for details.				



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ELECTRICAL CHARACTERISTICS

ltem	Symbol	Parameter	Conditions				Unit
No.				Min.	Тур.	Max.	
	Device		1			ſ	
001	VCC	Permissible VCC Supply Voltage		4.1		5.5	V
002	I(VCC)	VCC Supply Current	no load, Vout() < Vout()mx		9.5	15	mA
003	Vc()hi	Clamp-Voltage hi at all pins	I() = 4 mA			11	V
004	Vc()lo	Clamp-Voltage lo at all pins	l() = -4 mA	-1.2		-0.3	V
Photo	sensors						
101	λ ar	Spectral Application Range	$Se(\lambda ar) = 0.25 \times S(\lambda pk)$	400		950	nm
102	$S(\lambda)$	Spectral Sensitivity	λ_{LED} = 740 nm λ_{LED} = 850 nm, 460 nm		0.4 0.3		A/W A/W
103	λ pk	Peak Sensitivity Wavelength			680		nm
Photo	current Am	plifiers					
201	lph()	Permissible Photocurrent Operating Range		0		1120	nA
202	η()r	Photo Sensitivity (light-to-voltage conversion ratio)	λ_{LED} = 740 nm		0.3		V/µW
203	Z()	Equivalent Transimpedance Gain	Z = Vout() / Iph()	0.7	1.0	1.4	MΩ
204	TCz	Temperature Coefficient of Transimpedance Gain			-0.12		%/°C
205	ΔZ()pn	Transimpedance Gain Matching	P channel vs. corresponding N channel	-0.2		0.2	%
206	⊿Vout()pn	Signal Matching	no illumination; any output vs. any output P output vs. corresponding N output	-35 -2.5		35 2.5	mV mV
207	fc()hi	Cut-off Frequency (-3 dB)			400		kHz
208	VNoise()	RMS Output Noise	illuminated to 500 mV signal level above dark level, 500 kHz band width		0.5		mV
Signa	l Outputs						
301	Vout()mx	Permissible Max. Output Voltage		2.0			V
302	lout()mx	Permissible Max. Load Current		-100		250	μA
303	Vout()d	Dark Signal Level	no illumination, I() \leq 50 μ A	575	770	1000	mV
304	lsc()hi	Short-Circuit Current hi	load current to ground	100	420	1000	μA
305	lsc()lo	Short-Circuit Current lo	load current to IC	250	480	700	μA
306	Ri()	Internal Output Resistance	f=1kHz	70	110	180	Ω
307	ton()	Power-On Settling Time	$VCC = 0 V \rightarrow 5 V$			100	μs
Refer	ence Voltage		1	U	1		<u> </u>
401	VREF	Reference Voltage	I(VREF)= -100+300 μA	575	770	1000	mV
402	dVout()	Load Balancing	I(VREF) = -100+300 μA	-10		+10	mV
403	lsc()hi	Short-Circuit Current hi	load current to ground	200	420	1400	μA
404	lsc()lo	Short-Circuit Current lo	load current to IC	0.5	4.5	10	mA
Devic	e Specific: i	C-PN1864	1	п	1	<u> </u>	u
V101	Aph()	Radiant Sensitive Area	chip release Y		0.065		mm ²
	E()mxr	Irradiance For Max. Signal Level	λ_{LED} = 740 nm, Vout() not saturated; chip release Y		12		mW/ cm ²
Devic	e Specific: i	C-PN1856	1				
	Aph()	Radiant Sensitive Area	chip release Y		0.038		mm ²
	E()mxr	Irradiance For Max. Signal Level	λ_{LED} = 740 nm, Vout() not saturated; chip release Y	-	20		mW/
							cm ²
Devic	e Specific: i	C-PN2656					
V301	Aph()	Radiant Sensitive Area	chip release Z		0.11		mm ²
			chip release Y1		0.12		mm ²



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ELECTRICAL CHARACTERISTICS

tem	Symbol	Parameter	Conditions				Unit
lo.	-			Min.	Тур.	Max.	
V302	E()mxr	Irradiance For Max. Signal Level	λ_{LED} = 740 nm, Vout() not saturated;				
			chip release Z		6.4		mW
			chip release Y1		4.6		cm ² mW
					4.0		cm ²
Devic	e Specific:	iC-PN2612				Į	
	Aph()	Radiant Sensitive Area	chip release Z		0.08		mm ²
			chip release Y1		0.13		mm ²
V402	E()mxr	Irradiance For Max. Signal Level	λ_{LED} = 740 nm, Vout() not saturated;				
			chip release Z		8.0		mW
			chip release Y1		4.4		cm ² mW
					7.7		cm ²
Devic	e Specific:	iC-PN2624	1	I		1	
V501	Aph()	Radiant Sensitive Area	chip release Z		0.1		mm ²
			chip release Y1		0.07		mm
V502	E()mxr	Irradiance For Max. Signal Level	$\lambda_{\text{LED}} = 740 \text{ nm}, \text{ Vout() not saturated;}$		<u> </u>		
			chip release Z		6.5		mW cm ²
			chip release Y1		11.0		mW
							cm ²
Devic	e Specific:	iC-PN3356	1	1			1
V601	Aph()	Radiant Sensitive Area	chip release Z		0.08		mm
			chip release Y		0.10		mm
V602	E()mxr	Irradiance For Max. Signal Level	$\lambda_{\text{LED}} = 740 \text{ nm}, \text{ Vout() not saturated;}$				
			chip release Z		8.0		mW
			chip release Y		6.5		cm ² mW
					0.0		cm ²
Devic	e Specific:	iC-PN3312	1	I		1	
V701	Aph()	Radiant Sensitive Area	chip release Z		0.08		mm ²
			chip release Y		0.09		mm²
V702	E()mxr	Irradiance For Max. Signal Level	λ_{LED} = 740 nm, Vout() not saturated;				
			chip release Z		6.5		mW.
			chip release Y		7.0		mW
					1.0		cm ²
Devic	e Specific:	iC-PN3324	1	I		1	
V801	Aph()	Radiant Sensitive Area	chip release Z		0.05		mm ²
			chip release Y		0.09		mm²
V802	E()mxr	Irradiance For Max. Signal Level	$\lambda_{\text{LED}} = 740 \text{ nm}, \text{ Vout() not saturated;}$		40.0		
			chip release Z		13.0		mW mW
			chip release Y		7.0		mW
							cm ²
Devic	e Specific:	iC-PN3924	·				
V901	Aph()	Radiant Sensitive Area	chip release Z		0.09		mm
			chip release Y		0.11		mm ²
V902	E()mxr	Irradiance For Max. Signal Level	λ_{LED} = 740 nm, Vout() not saturated;		. .		
			chip release Z		6.4		mW cm ²
			chip release Y		5.8		mW

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DEVICE OVERVIEW

Device	CPR	Code Disc		OR ¹	Code Radius	Resol. ²	Error Tol. ³
	Master	P/O Code	Material	[mm]	begin/end [mm]	[bit]	[el.deg.]
				1	<u> </u>		
Ø 18 Series		(disc diameter 18 mm	, bore hole	e 3.0 mm)		
iC-PN1864	64	LSHC16S 18-64N	glass	6.905	5.3 / 8.4	19	± 19.6
iC-PN1856	256	LSHC15S 18-256	glass	6.905	5.3 / 8.4	21	± 9.8
					-		
\varnothing 26 Series		(disc diameter 26.0 m	m, bore h	ole 11.6 n	nm)		
iC-PN2656	256	LSHC4S 26-256N	glass	10.905	9.3 / 12.5	21	± 9.8
iC-PN2612	512		glass	10.905	9.3 / 12.5	22	± 4.9
iC-PN2624	1024	LSHC1S 26-1024N	glass	10.905	9.3 / 12.5	23	\pm 4.9
H-Series ⁴		(disc diameter 26.0 m			,		
iC-PNH2628	2x64	PNH6S 26-128	glass	10.905	9.4 / 12.4	20	± 19.6
iC-PNH2612	2x256	PNH3S 26-512	glass	10.905	9.4 / 12.4	22	± 9.8
iC-PNH2624	2x512	PNH5S 26-1024	glass	10.905	9.4 / 12.4	23	± 4.9
Ø 33 Series		(disc diameter 33.0 m			,		
iC-PN3356	256		glass	14.5	12.9 / 16.1	21	± 9.8
iC-PN3312	512		glass	14.5	12.9 / 16.1	22	± 4.9
iC-PN3324	1024	LSHC10S 33-1024N	glass	14.5	12.9 / 16.1	23	± 4.9
H-Series ⁴		(disc diameter 33.2 m	m bore h	ole 18 0 r	nm)		
iC-PNH3312	2x256	PNH2S 33-512	glass	14.5	13.0 / 16.0	22	± 9.8
iC-PNH3348 ⁵	2x1024	PNH1S 33-2048	glass	14.5	13.0 / 16.0	24	± 4.9
			9.000				
Ø 39 Series		(disc diameter 39.0 m	m, bore h	ole 13.0 r	nm)		
iC-PN3924	1024		glass	17.5	15.9 / 19.1	23	± 4.9
			0				
H-Series ⁴		(disc diameter 39.0 m	m, bore h	ole 18.0 r	nm)		
iC-PNH3912	2x256	· · · · · · · · · · · · · · · · · · ·	glass	17.5	16.0 / 19.0	22	± 4.9
iC-PNH3948	2x1024	PNH4S 39-2048	glass	17.5	16.0 / 19.0	24	± 4.9
	1	1	-	1	1	1	
¹ Optical cente	r radius.						
² Angle resolut	ion per sii	ngle turn; interpolated b	oy iC-MN	with 13 bi	t resolution.		
³ Permissible n	naximum	track-to-track phase de	eviation in	electrica	l degree per maste	er signal cy	/cle.

⁴ Refer to iC-PNH Series datasheet available separately.

⁵ EncoderBlue[®] component. EncoderBlue is a trademark of iC-Haus GmbH.

Device availability on request.

Table 4: Device overview



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APPLICATION CIRCUITS

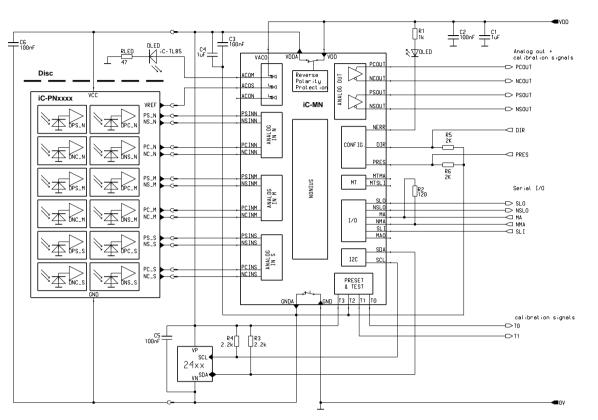


Figure 1: Application example of absolute encoder circuit.



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DESIGN REVIEW: Notes On Chip Functions

iC-PNxxxx.					
No.	Function, Parameter/Code	Description and Application Hints			
1		Refer to former datasheet releases.			

Table 5: Notes on chip functions regarding iC-PNxxxx chip releases 0.

iC-PNxxxx Z					
No.	Function, Parameter/Code	Description and Application Hints			
1		Changes to Elec. Char. are documented by this datasheet release, including the extension of operating voltage down to 4.1 V (safe by design).			

Table 6: Notes on chip functions regarding iC-PNxxxx chip release Z.

iC-PNxxxx Y1					
No.	Function, Parameter/Code	Description and Application Hints			
1	HD Phased Array	Chip release utilizes a high definition phased array layout.			

Table 7: Notes on chip functions regarding iC-PNxxxx chip release Y1.

REVISION HISTORY

Rel.	Rel. Date ¹	Chapter	Modification	Page
A1	2008		Initial introduction.	

Rel.	Rel. Date ¹	Chapter	Modification	Page
E1	2017-02-08		New datasheet for iC-PN chip series	all

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ORDERING INFORMATION

Туре	Package	Options	Order Designation
iC-PNnnnn	15-pin optoBGA, 6.2 mm x 5.2 mm, thickness 1.7 mm RoHS compliant	nnnn = device version	iC-PNnnnn oBGA LSH2C
iC-PNnnnn	32-pin optoQFN, 5 mm x 5 mm, thickness 0.9 mm RoHS compliant	nnnn = device version	iC-PNnnnn oQFN32-5x5
Code Disc	Glass disc 1.0 mm	nn = design number aa = diameter xxxx = master track CPR	LSHCnnS aa-xxxxN
		for iC-PN1864 (64 CPR) for iC-PN1856 (256 CPR) for iC-PN2656 (256 CPR) for iC-PN2612 (512 CPR) for iC-PN2624 (1024 CPR) for iC-PN3312 (512 CPR) for iC-PN3324 (1024 CPR) for iC-PN3356 (256 CPR) for iC-PN3924 (1024 CPR)	LSHC9S 33-512N LSHC10S 33-1024N LSHC13S 33-256N
Evaluation Kit	Kit with Scanner Module IC273 (61 mm x 64 mm), LED Module IC274 and Code Disc		iC-PNnnnn EVAL IC273 iC-PN2656 EVAL IC273
Illumination	IR LED module (28 mm x 29 mm) Blue LED module (28 mm x 29 mm)	with iC-SD85 (850 nm) with iC-TL46 (460 nm)	iC-SD85 EVAL IC274 iC-TL46 EVAL IC274
Mother Board Adapter Board	Adapter PCB (80 mm x 110 mm) Adapter PCB (41 mm x 41 mm), connects IC273 to MN1D	incl. ribbon cable incl. ribbon cable	iC277 EVAL IC277 iC306 EVAL IC306

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